



PRODUCT SHEET

VISHAY – Basic Commodity MLCC

PART NUMBER	VJ1812Y473KXETW1BC
SIZE	: 1812
CERAMIC	: «Y» = X7R
CAPACITANCE	: « 473 » = 47nF
TOLERANCE	: « K » = +/- 10%
TERMINATION	: « X » = Ni-Barrier with 100% Tin termination
VOLTAGE	: « E » = 500 Volt DC
PACKAGING	: « T » = 7" reel - PU : 1000 pcs.
PROCESS CODE	: «W1BC » = Vishay Basic Commodity

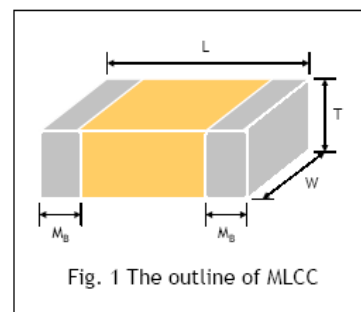


RoHS
COMPLIANT
HALOGEN
FREE
GREEN
(5-2008)

Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

DIMENSIONS

LENGTH	: 4.50 mm + 0.5 / -0.3 mm
WIDTH	: 3.20 mm +/- 0.30 mm
THICKNESS	: 1.25 mm +/- 0.10 mm
M_B	: 0.50 mm +/- 0.25 mm



THICKNESSCODE : D
Note : Reflow soldering process only

GENERAL ELECTRICAL DATA

Dielectric	NP0	X7R	Y5V
Size	0603, 0805, 1206, 1210, 1808, 1812		0805, 1206, 1210, 1812
Capacitance*	0.5pF to 6800pF	100pF to 1.0μF	0.01μF to 0.68μF
Capacitance tolerance***	Cap≤5pF: C (±0.25pF) 5pF<Cap<10pF: D (±0.5pF) Cap≥10pF: F (±1%), G (±2%), J (±5%),K (±10%)	K (±10%), M (±20%)	Z (-20/+80%)
Rated voltage (WVDC)	200V to 3kV		200V, 250V
Q*	Cap<30pF: Q≥400+20C Cap≥30pF: Q≥1000	≤2.5%	≤5%
Insulation resistance at Ur**	Ur=200~630V: ≥10GΩ or RxC≥100Ω·F whichever is smaller Ur=1000~3000V: ≥10GΩ		
Dielectric strength	200~300V: ≥2 x WVDC 500~999V: ≥1.5 x WVDC 1000~3000V: ≥1.2 x WVDC		
Operating temperature	-55 to +125°C		-25 to +85°C
Capacitance characteristic	±30ppm	±15%	+30/-80%
Termination	Ni/Sn (lead-free termination)		

* Measured at the condition of 30~70% related humidity.

NP0: Apply 1.0±0.2Vrms, 1.0MHz±10% for Cap≤1000pF and 1.0±0.2Vrms, 1.0kHz±10% for Cap>1000pF, 25°C at ambient temperature

X7R, Y5V: Apply 1.0±0.2Vrms, 1.0kHz±10%, at 20°C ambient temperature.

** Measured at 500VDC for 60 sec. for Ur>500VDC.

*** Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in ambient condition for 24±2 hours before measurement.



RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	Item	Test Condition	Requirements																
1.	Visual and Mechanical	—	No remarkable defect. Dimensions to conform to individual specification sheet.																
2.	Capacitance	Class I: (NP0)	Shall not exceed the limits given in the detailed spec.																
3.	Q/ D.F. (Dissipation Factor)	Cap≤1000pF, 1.0±0.2Vrms, 1MHz±10% Cap>1000pF, 1.0±0.2Vrms, 1KHz±10% Class II: (X7R, Y5V) 1.0±0.2Vrms, 1kHz±10%	NP0: Cap≥30pF, Q≥1000; Cap<30pF, Q≥400+20C X7R: ≤2.5% Y5V: ≤5.0%																
4.	Dielectric Strength	To apply voltage: 200V~300V ≥2 times VDC 500V~999V ≥1.5 times VDC 1000V~3000V ≥1.2 times VDC Cut-off, set at 10mA TEST= 15 sec. RAMP=0	No evidence of damage or flash over during test.																
5.	Insulation Resistance	Rated voltage: 200~630V To apply rated voltage (500V max.) for 60 sec. Rated voltage: ≥630V To apply 500V for 60 sec.	≥10GΩ or RxC≥100Ω-F whichever is smaller ≥10GΩ																
6.	Temperature Coefficient	With no electrical load. <table><tr><th>T.C.</th><th>Operating Temp</th></tr><tr><td>NP0</td><td>-55~125°C at 25°C</td></tr><tr><td>X7R</td><td>-55~125°C at 25°C</td></tr><tr><td>Y5V</td><td>-25~85°C at 20°C</td></tr></table>	T.C.	Operating Temp	NP0	-55~125°C at 25°C	X7R	-55~125°C at 25°C	Y5V	-25~85°C at 20°C	<table><tr><th>T.C.</th><th>Capacitance Change</th></tr><tr><td>NP0</td><td>Within ±30ppm/°C</td></tr><tr><td>X7R</td><td>Within ±15%</td></tr><tr><td>Y5V</td><td>Within +30%/-80%</td></tr></table>	T.C.	Capacitance Change	NP0	Within ±30ppm/°C	X7R	Within ±15%	Y5V	Within +30%/-80%
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Y5V	Within +30%/-80%																		
7.	Adhesive Strength of Termination	Pressurizing force : 5N (≤0603) and 10N (>0603) Test time: 10±1 sec.	No remarkable damage or removal of the terminations.																
8.	Vibration Resistance	Vibration frequency: 10~55 Hz/min. Total amplitude: 1.5mm Test time: 6 hrs. (Two hrs each in three mutually perpendicular directions.) Measurement to be made after keeping at room temp. for 24±2 hrs.	No remarkable damage. Cap change and Q/D.F.: To meet initial spec.																
9.	Solderability	Solder temperature: 235±5°C Dipping time: 2±0.5 sec.	95% min. coverage of all metalized area.																
10.	Bending Test	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm per second until the deflection becomes 1 mm and then the pressure shall be maintained for 5±1 sec. Measurement to be made after keeping at room temp. for 24±2 hrs.	No remarkable damage. Cap change : NP0: within ±5.0% or ±0.5pF whichever is larger. X7R: within ±12.5% Y5V: within ±30% (This capacitance change means the change of capacitance under specified flexure of substrate from the capacitance measured before the test.)																
11.	Resistance to Soldering Heat	Solder temperature: 260±5°C Dipping time: 10±1 sec Preheating: 120 to 150°C for 1 minute before immerse the capacitor in a eutectic solder. Before initial measurement (Class II only): Perform 150+0/-10°C for 1 hr and then set for 24±2 hrs at room temp. Measurement to be made after keeping at room temp. for 24±2 hrs.	No remarkable damage. Cap change: NP0: within ±2.5% or ±0.25pF whichever is larger. X7R: within ±7.5% Y5V: within ±20% Q/D.F., I.R. and dielectric strength: To meet initial requirements. 25% max. leaching on each edge.																



No.	Item	Test Condition	Requirements															
12.	Temperature Cycle	<p>* Conduct the five cycles according to the temperatures and time.</p> <table><tr><th>Step</th><th>Temp. (°C)</th><th>Time (min.)</th></tr><tr><td>1</td><td>Min. operating temp. +0/-3</td><td>30±3</td></tr><tr><td>2</td><td>Room temp.</td><td>2~3</td></tr><tr><td>3</td><td>Max. operating temp. +3/-0</td><td>30±3</td></tr><tr><td>4</td><td>Room temp.</td><td>2~3</td></tr></table> <p>* Before initial measurement (Class II only): Perform 150+0/-10°C for 1 hr and then set for 24±2 hrs at room temp.</p> <p>* Measurement to be made after keeping at room temp. for 24±2 hrs.</p>	Step	Temp. (°C)	Time (min.)	1	Min. operating temp. +0/-3	30±3	2	Room temp.	2~3	3	Max. operating temp. +3/-0	30±3	4	Room temp.	2~3	<p>No remarkable damage.</p> <p>Cap change :</p> <p>NP0: within ±2.5% or ±0.25pF whichever is larger.</p> <p>X7R: within ±7.5%</p> <p>Y5V: within ±20%</p> <p>* Q/D.F., I.R. and dielectric strength: To meet initial requirements.</p>
Step	Temp. (°C)	Time (min.)																
1	Min. operating temp. +0/-3	30±3																
2	Room temp.	2~3																
3	Max. operating temp. +3/-0	30±3																
4	Room temp.	2~3																
13.	Humidity (Damp Heat) Steady State	<p>* Test temp.: 40±2°C</p> <p>* Humidity: 90~95% RH</p> <p>* Test time: 500+24/-0hrs.</p> <p>* Before initial measurement (Class II only): Perform 150+0/-10°C for 1 hr and then set for 24±2 hrs at room temp.</p> <p>* Measurement to be made after keeping at room temp. for 24±2 hrs.</p>	<p>* No remarkable damage.</p> <p>* Cap change: NP0: within ±5.0% or ±0.5pF whichever is larger.</p> <p>X7R: within ±12.5%</p> <p>Y5V: within ±30%</p> <p>* Q/D.F. value:</p> <p>NP0: Cap≥30pF, Q≥350; 10pF≤Cap<30pF, Q≥275+2.5C</p> <p>Cap<10pF; Q≥200+10C</p> <p>X7R: ≤3.0%</p> <p>Y5V: ≤7.5%</p> <p>* I.R.: ≥1GΩ or RxC≥50Ω-F whichever is smaller.</p>															
14.	Humidity (Damp Heat) Load	<p>* Test temp.: 40±2°C</p> <p>* Humidity: 90~95%RH</p> <p>* Test time: 500+24/-0 hrs.</p> <p>* To apply voltage : rated voltage (Max. 500V)</p> <p>* Before initial measurement (Class II only): To apply test voltage for 1hr at 40°C and then set for 24±2 hrs at room temp.</p> <p>* Measurement to be made after keeping at room temp. for 24±2 hrs.</p>	<p>* No remarkable damage.</p> <p>* Cap change: NP0: within ±7.5% or ±0.75pF whichever is larger.</p> <p>X7R: within ±12.5%</p> <p>Y5V: within ±30%</p> <p>* Q/D.F. value:</p> <p>NP0: Cap≥30pF, Q≥200; Cap<30pF, Q≥100+10/3C</p> <p>X7R: ≤3.0%</p> <p>Y5V: ≤7.5%</p> <p>* I.R.: ≥500MΩ or RxC≥25Ω-F whichever is smaller.</p>															
15.	High Temperature Load (Endurance)	<p>* Test temp.: NP0, X7R: 125±3°C Y5V: 85±3°C</p> <p>* To apply voltage:</p> <p>(1) <500V: 200% of rated voltage.</p> <p>(2) 500V: 150% of rated voltage.</p> <p>(3) ≥630V: 120% of rated voltage.</p> <p>(4) 1206,NP0 ≥1.5pF: 100% of rated voltage.</p> <p>* Test time: 1000+24/-0 hrs.</p> <p>* Before initial measurement (Class II only): To apply test voltage for 1hr at test temp. and then set for 24±2 hrs at room temp.</p> <p>* Measurement to be made after keeping at room temp. for 24±2 hrs</p>	<p>* No remarkable damage.</p> <p>* Cap change: NP0: within ±3.0% or ±0.3pF whichever is larger.</p> <p>X7R: within ±12.5%</p> <p>Y5V: within ±30%</p> <p>* Q/D.F. value:</p> <p>NP0: Cap≥30pF, Q≥350</p> <p>10pF≤Cap<30pF, Q≥275+2.5C</p> <p>Cap<10pF, Q≥200+10C</p> <p>X7R: ≤3.0%</p> <p>Y5V: ≤7.5%</p> <p>* I.R.: ≥1GΩ or RxC≥50Ω-F whichever is smaller.</p>															

TAPE & REEL DIMENSIONS (in mm)

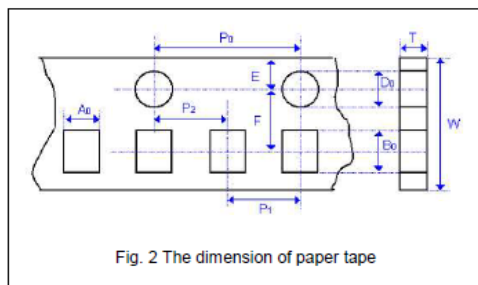


Fig. 2 The dimension of paper tape

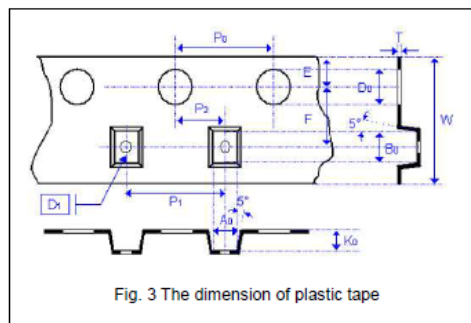


Fig. 3 The dimension of plastic tape

Size	0603	0805		1206			1210		1808		1812
Thickness	S, X	B	C, D, I	B	C, D	G	C, D, G	M	D	K	D, K
A ₀	1.02±0.05	1.50±0.10	<1.57	2.00±0.10	<1.85	<1.95	<2.97	<2.97	<2.35	<2.35	<3.81
B ₀	1.80±0.05	2.30±0.10	<2.40	3.50±0.10	<3.46	<3.67	<3.73	<3.73	<4.98	<5.00	<5.30
T	0.95±0.05	0.95±0.05	0.23±0.05	0.95±0.05	0.23±0.05	0.23±0.05	0.23±0.05	0.23±0.05	0.25±0.05	0.25±0.05	0.25±0.05
K ₀	-	-	<2.50	-	<2.50	<2.50	<2.50	<3.0	<2.50	<2.50	<2.50
W	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	12.0±0.20	12.0±0.20	12.0±0.20
P ₀	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.100	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
10xP ₀	40.0±0.10	40.0±0.10	40.0±0.10	40.0±0.10	40.0±0.10	40.0±0.10	40.0±0.10	40.0±0.10	40.0±0.10	40.0±0.10	40.0±0.10
P ₁	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	8.00±0.10
P ₂	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05
D ₀	1.55±0.05	1.55±0.05	1.50±0.05	1.50±0.05	1.50±0.05	1.50±0.05	1.50±0.05	1.50±0.05	1.50±0.05	1.50±0.05	1.50±0.05
D ₁	-	-	1.00±0.10	-	1.00±0.10	1.00±0.10	1.00±0.10	1.00±0.10	1.50±0.10	1.50±0.10	1.50±0.10
E	1.75±0.05	1.75±0.05	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10
F	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	5.50±0.05	5.50±0.05	5.50±0.05

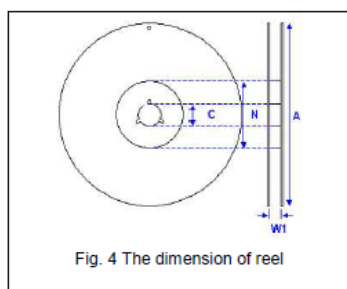


Fig. 4 The dimension of reel

Size	0603, 0805, 1206, 1210			1808, 1812
Reel size	7"	10"	13"	7"
C	13.0±0.5/-0.2	13.0±0.5/-0.2	13.0±0.5/-0.2	13.0±0.5/-0.2
W ₁	8.4±1.5/-0	8.4±1.5/-0	8.4±1.5/-0	12.4±2.0/-0
A	178.0±0.10	250±1.0	330±1.0	178.0±0.10
N	60.0±1/-0	100±1.0	100±1.0	60.5±1.0

Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70% related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

- The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

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Vishay:

VJ1812Y473KXETW1BC